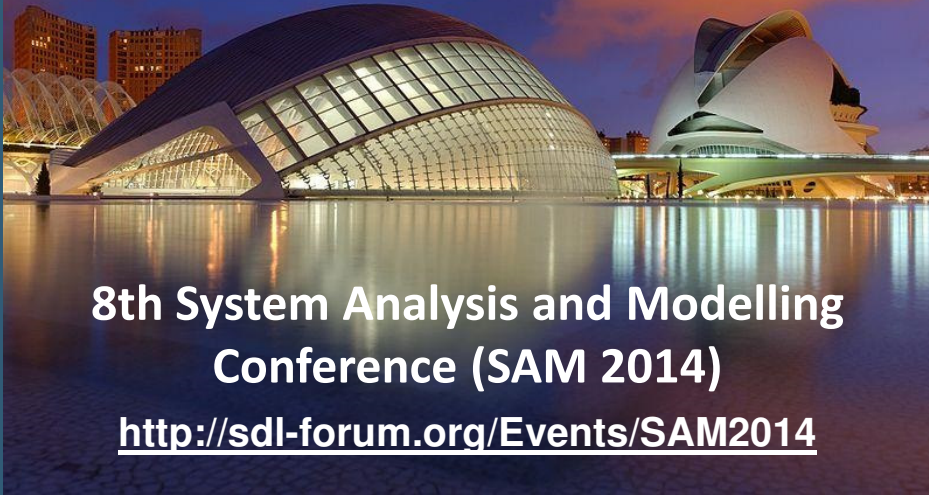


September 29-30, 2014. Valencia, Spain.
co-located with MODELS



8th System Analysis and Modelling Conference (SAM 2014)

<http://sdl-forum.org/Events/SAM2014>

The System Analysis and Modelling (SAM) conference provides an open arena for participants from academia and industry to present and discuss the most recent innovations, trends, experiences and concerns in *modelling, specification and analysis* of distributed, communication and real-time systems using ITU-T Specification and Description Language and Message Sequence Chart notations, as well as related system design languages (including but not limited to UML, ASN.1, TTCN, SysML and URN).

The SAM conference originates from the use of languages and techniques for telecommunications applications, whereas MODELS has a background in the application of UML. However, UML is also used for telecommunications, and the languages standardized by ITU-T (ASN.1, SDL-2010, MSC, TTCN-3, URN) are also used for other applications. The 2014 MODELS conference week is a unique opportunity to attend both of these events with overlapping domains of interest.

Theme: Models and Reusability

Model reuse is a powerful concept defined as the process of creating new models using existing model artefacts. To make model reuse applicable, reusing an artefact should be easier than constructing it from scratch. This entails that the reusable artefacts are easy to understand, find and apply. Commonly reusable artefacts include classes, components, patterns, frameworks and services, and emerging ones include product lines, aspects and concerns. SAM 2014 invites contributions related to the reuse of model artefacts and the design of reusable artefacts for ITU-T languages and other related system design languages.

Scope

The 2014 edition of the conference will cover the following non-exhaustive list of topics: *models and reusability, language development, model-driven development and applications*. See the conference website for more details.

Submission and Publication

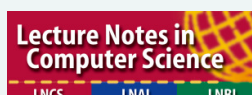
Submissions must be previously unpublished, written in English, no longer than **16 pages** (including illustrations and bibliography) and using the LNCS style as described in the LNCS Author and Editor Guidelines. Authors are strongly encouraged to use the LaTeX version of the template. Papers accepted or under review for other events are ineligible for submission to SAM 2014. Submissions in the following categories are solicited:

Full papers describing original, unpublished results (max. 16 pages in LNCS style)

Short papers describing work in progress (max. 8 pages in LNCS style)

The SAM 2014 Program Committee will evaluate the technical contribution of each submission as well as its accessibility to the audience. Papers will be judged on significance, originality, substance, correctness and clarity.

As in previous editions, the SAM 2014 proceedings will be published in the Springer LNCS series.



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IMPORTANT DATES in 2014

MAY 26	ABSTRACT SUBMISSION	JUNE 2	PAPER SUBMISSION
JUNE 23	ACCEPTANCE NOTIFICATION	JULY 7	CAMERA-READY VERSION

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